

General Description

The SJD60P110 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

Features

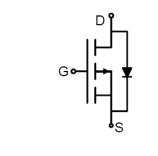
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

Load Switch

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	-60	V
R _{DS(ON)_TYP}	11	mΩ
ID	-60	А
Q _G	140	nC







Schematic Diagram

TO-252(DPAK) top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD60P110	SJD60P110	TO-252	Таре	١	١	2500 Pcs

Table 1. Absolute Maximum Ratings ($T_c=25^{\circ}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	-60	V
V _{GS}	Gate-Source Voltage (V _{DS} =0V)	±20	V
Ŀ	Drain Current-Continuous(Tc=25°C)		А
ID	Drain Current-Continuous(T _C =100℃)	-38	А
DM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-240	А
P	Maximum Power Dissipation(Tc=25 $^\circ\!\!\!\mathrm{C}$)	89	W
PD	Maximum Power Dissipation(Tc=100°C)	36	W
E _{AS}	Avalanche energy (Note 2)	484	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	c

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R _θ JC	Thermal Resistance, Junction-to-Case		1.4	°C/W



Table 3. Electrical Characteristics (T_J=25 $^{\circ}$ C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250µA	-60			V
	Zero Gate Voltage Drain Current	V _{DS} =-60V, V _{GS} =0V TJ=25℃			-1	μA
IDSS		V _{DS} =-60V, V _{GS} =0V TJ=125℃			-100	μA
lgss	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250µA	-1	-1.8	-2.5	V
G FS	Forward Transconductance	V _{DS} =-5V, I _D =-20A		38		S
Rds(on)	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-15A T _J =25℃		11	14.3	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-10A T _J =25℃		14.3	19	mΩ
Dynamic Chara	icteristics			•		
Ciss	Input Capacitance			8700		pF
Coss	Output Capacitance	V _{DS} =-30V,V _{GS} =0V, f=1.0MHz		290		pF
Crss	Reverse Transfer Capacitance			210		pF
Switching Para	meters			•		•
t _{d(on)}	Turn-on Delay Time			26		nS
tr	Turn-on Rise Time	V _{GS} =-10V, V _{DS} =-30V, R _L =1.5Ω, R _{GEN} =3Ω		21		nS
t _{d(off)}	Turn-Off Delay Time			138		nS
t _f	Turn-Off Fall Time			30		nS
Qg	Total Gate Charge			140		nC
Q _{gs}	Gate-Source Charge	V _{GS} =-10V, V _{DS} =-30V, I _D =-20A		19		nC
Q _{gd}	Gate-Drain Charge			28		nC
Source-Drain D	iode Characteristics					
I _{SD}	Source-Drain Current (Body Diode)				-60	А
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =-20A			-1.2	V
trr	Reverse Recovery Time	I⊧=-20A, di/dt=-100A/µs		56		ns
Qrr	Reverse Recovery Charge	I _F =-20A, di/dt=-100A/µs		63		nC

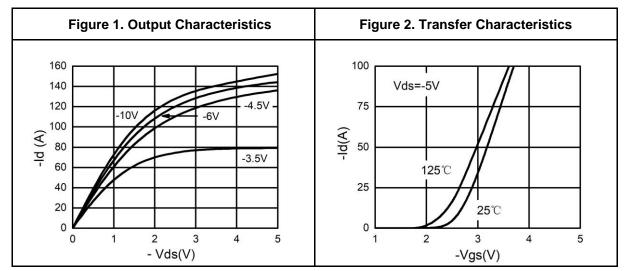
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature. Notes 2.E_{AS} condition: T_J=25°C,V_{DD}=-40V,V_G=-10V, Rg=25\Omega, L=0.5mH. Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

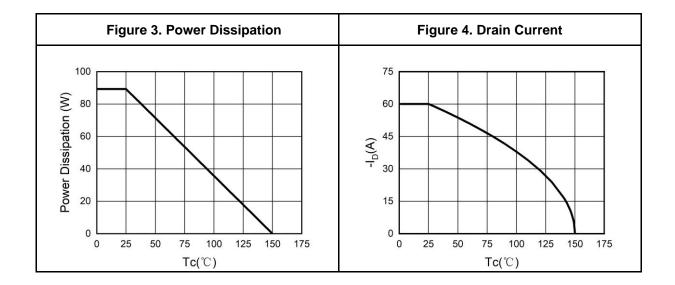


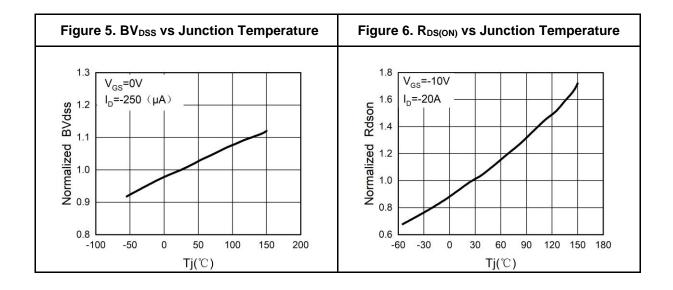
SJD60P110

60V P-Channel Trench Power MOSFET

Typical Electrical And Thermal Characteristics (Curves)



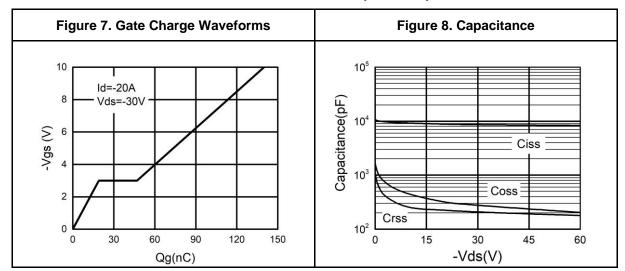


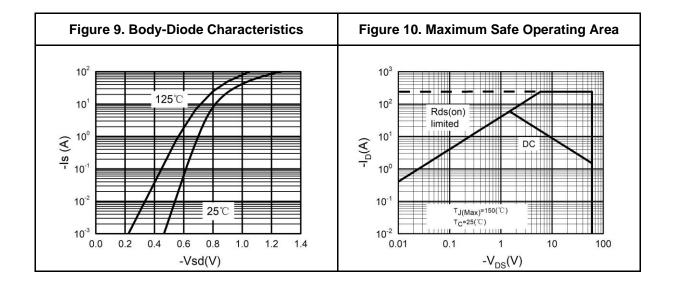




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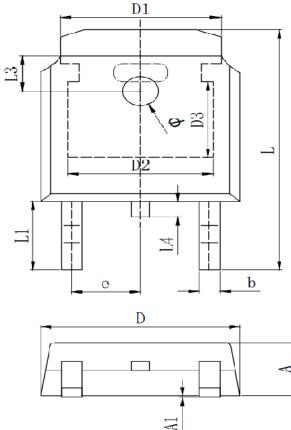
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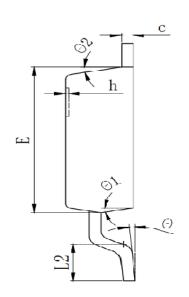






TO-252 Package Information





Symbol	Dimensions In Millimeters			
Symbol	Min.	Тур.	Max.	
А	2.200	2.300	2.400	
A1	0.000		0.127	
b	0.640	0.690	0.740	
c(电镀后)	0.460	0.520	0.580	
D	6.500	6.600	6.700	
D1	5.334 REF			
D2	4.826 REF			
D3	3.166 REF			
E	6.000	6.100	6.200	
е		2.286 TYP		
h	0.000	0.100	0.200	
L	9.900	10.100	10.300	
L1		2.888 REF		
L2	1.400	1.550	1.700	
L3		1.600 REF		
L4	0.600	0.800	1.000	
Φ	1.100	1.200	1.300	
θ	0°		8°	
θ1	9° TYP			
θ2	9° TYP			



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